

1 ROHS

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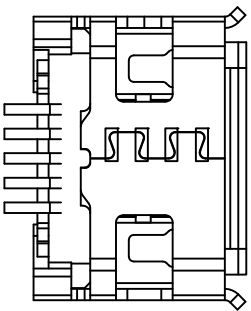
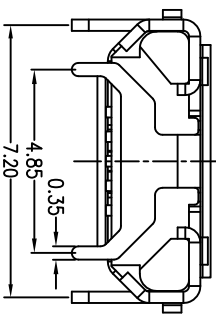
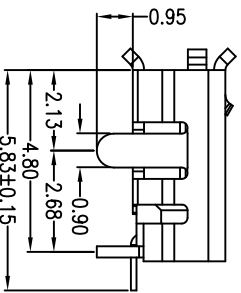
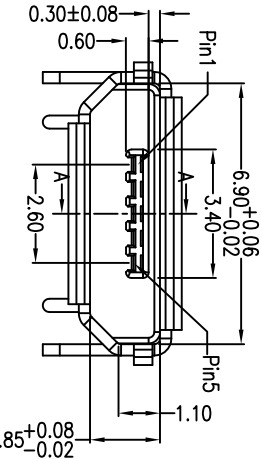
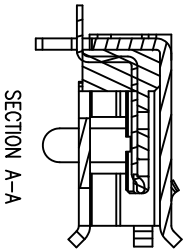
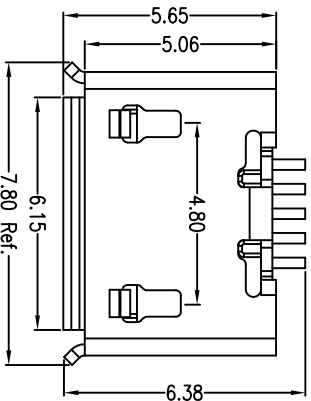
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MAPX

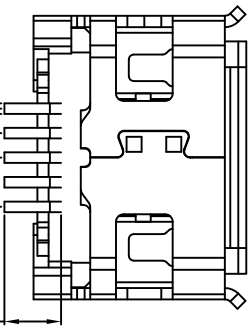
MODIFICATION

DRW

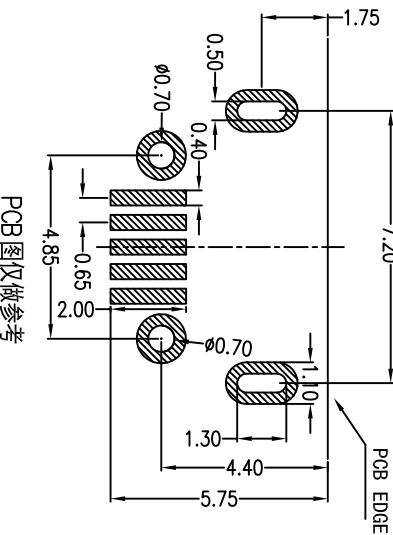
DATE



不锈钢及铜合



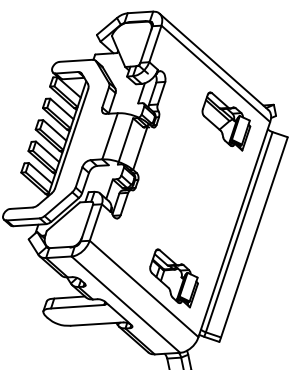
铜壳单脚合



PCB图仅做参考

Note:

1. Material:
 - 1.1 Housing: High temperature thermoplastic with g.f.U.L94V-0
 - 1.2 Contact: copper alloy,t=0.15mm
 - 1.3 Shell: copper alloy,t=0.30mm
2. Specification:
 - 2.1 Current rating:1.5PIN 1.8A Max/2.3,4PIN 1A Max. voltage: 100 V(ac) for 1 min.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 mΩ Max.
 - 2.4 Insulation resistance: 100 MΩ Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min.
 - 2.7 Temperature range: -30C~80C



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产品图

公差一览表

TOLERANCE UNLESS OTHERWISE	公差
X	±0.35
X	±0.20
XX	±0.15
XXX	±0.05

深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.

单位	MM	制图	许榕强	制图料号
比例	1:1	审核	郭治富	产品名称
日期	2016-09-09	核准	黄国荣	角法
DATE		APRD		版本
				A0

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